

SGK5867-100A/001

C-Band Internally Matched Gan-HEMT

Features

High Output Power: P5dB=50.5dBm (Typ.)

High Linear Gain: GL=13.5dB (Typ.)

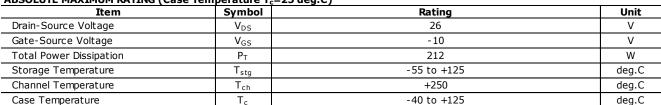
• High Power Added Efficiency: PAE=45% (Typ.)

· Broad Band: 5.85 to 6.75GHz Hermetically Sealed Package



The SGK5867-100A/001 is a high power GaN-HEMT that is internally matched for standard communication bands to provide optimum power and gain in a 50ohm system.





RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit
Drain-Source Voltage	V_{DS}		<=24	V
Forward Gate Current	I_{GF}	Rg=15ohm	<=24.4	mA
Reverse Gate Current	I_{GR}	Rg=15ohm	>=-12.8	mA
Channel Temperature	T _{ch}		<+192	deg.C

ELECTRICAL CHARACTERISTICS (Case Temperature T_c=25 deg.C)

Thomas	Cumbal	Condition Condition	Limit			Unit
Item	Symbol	Condition	Min.	Тур.	Max.	
Saturated Drain Current	I _{DSS}	V _{DS} =10V, V _{GS} =0V	-	26	-	Α
Trans Conductance	G _m	V _{DS} =24V, I _{DS} =5.3A	-	12	-	S
Pinch-off Voltage	V _P	V_{DS} =24V, I_{DS} =5.3mA	-	-3	-	V
Output Power at 5dB G.C.P.	P _{5dB}		49.5	50.5	-	dBm
Linear Gain at Pin=26.5dBm	GL	$V_{DS}=24V(typ.)$	12.5	13.5	-	dB
Drain Current at 5dB G.C.P.	I _{DSR}	I _{DS(DC)} =4.0A(typ.) f=5.85 to 6.75 GHz	-	10	14	Α
Power Added Efficiency at 3dB G.C.P.	PAE	Vgs-constant	-	45	-	%
Gain Flatness	ΔG	- 195 constant	-	-	1.6	dB
3rd Order Inter Modulation Distortion	IM ₃	f=5.85GHz, 6.75GHz Δf=10MHz, 2-tone Test Pout=44.0dBm (S.C.L.)	-25.0	-	-	dBc
Thermal Resistance	R _{th}	Channel to Case (T _c =25deg.C, Pdiss=96W)	-	0.55	0.75	deg.C/W
Channel Temperature Rise	ΔT_{ch}	(V _{DS} x I _{DSR} - Pout + Pin) x R _{th}	-	85	140	deg.C
<u> </u>		C C D + Cain Comm	roccion Do	:n+ C C I	. Cinala	Carrier Level

G.C.P.: Gain Compression Point, S.C.L.: Single Carrier Level

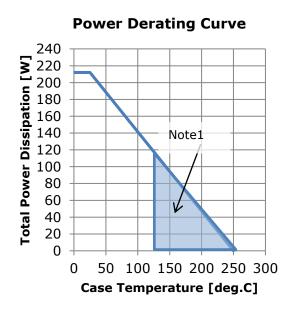
CASE STYLE	I2F	
RoHS Compliance	YES	
ESD	Class 1C	1000V to < 2000V

Note: Based on ANSI/ESDA/JEDEC JS-001-2012(C=100pF, R=1.5kohm)

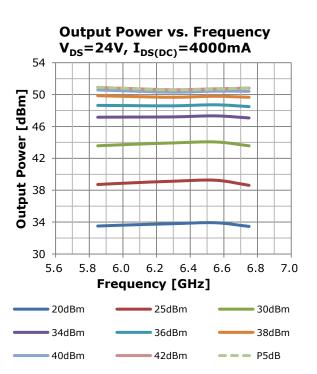




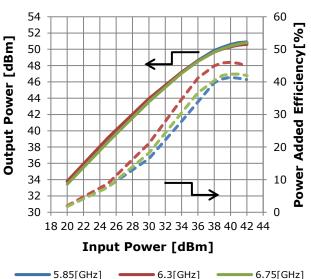
RF Characteristics



Note 1: Shaded area exceeds Maximum Case Temperature (See Page1)

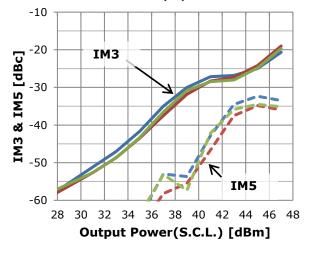


Input Power vs. Output Power and **Power Added Efficiency** $V_{DS} = 24V, I_{DS(DC)} = 4000 mA$



- 6.3[GHz] - 6.75[GHz]

IMD vs. Output Power $V_{DS} = 24V, I_{DS(DC)} = 4000mA$

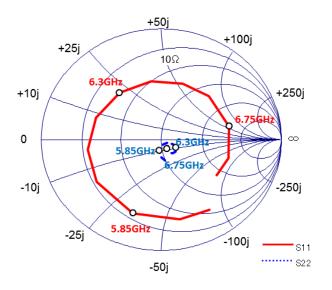


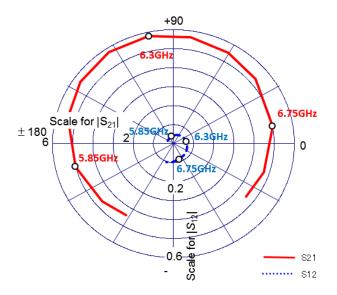
• 6.3[GHz]

5.85[GHz]



• S-Parameter





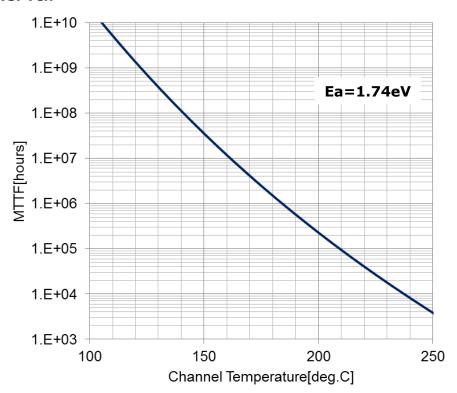
Freq.	S11		S21		S12		S22	
-	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
5600 MHz	0.746	-57.6	4.452	-121.9	0.033	151.9	0.190	-81.4
5700 MHz	0.736	-77.9	4.653	-139.3	0.035	132.6	0.157	-90.8
5850 MHz	0.704	-109.6	5.021	-166.0	0.040	103.8	0.098	-100.8
6000 MHz	0.657	-144.9	5.425	165.3	0.047	73.5	0.044	-71.4
6100 MHz	0.617	-171.5	5.652	144.9	0.053	52.3	0.063	-25.8
6200 MHz	0.579	159.6	5.781	123.7	0.059	31.1	0.107	-22.5
6300 MHz	0.548	129.4	5.789	102.3	0.065	10.2	0.140	-31.2
6400 MHz	0.531	99.2	5.684	81.2	0.070	-10.1	0.157	-41.8
6500 MHz	0.535	70.4	5.510	60.4	0.075	-29.0	0.153	-51.9
6600 MHz	0.556	44.7	5.310	40.2	0.080	-46.6	0.135	-59.5
6750 MHz	0.579	12.0	4.994	10.6	0.087	-71.2	0.095	-59.8
6900 MHz	0.582	-16.3	4.716	-18.4	0.097	-94.1	0.080	-47.1
7000 MHz	0.560	-35.0	4.552	-37.7	0.105	-109.9	0.078	-58.1

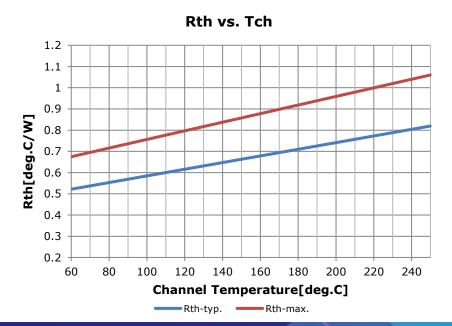


Rth of 100W class IM-GaN device at CW operation

Condition: Wdiss=96W, Rth-typ.=0.55deg.C/W @Tc=25deg.C, Rth-max.=0.75deg.C/W @Tc=25deg.C

MTTF vs. Tch

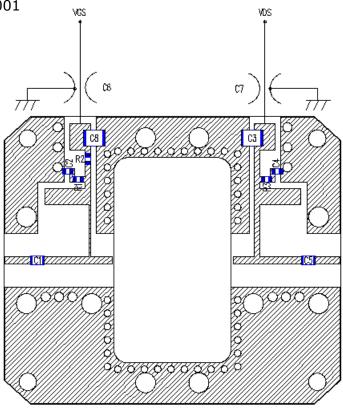






• Amplifier Circuit Outline

SGK5867-100A/001



C1	3.0pF
C2	1000pF
C3	0.1uF
C4	1000pF
C5	3.0pF
C6	1000pF
C7	1000pF
C8	0.1uF
R1	51ohm
R2	15ohm
R3	51ohm

Substrate : Rogers RO4003C h=0.542mm, $\epsilon r=3.38$ Cu=18um

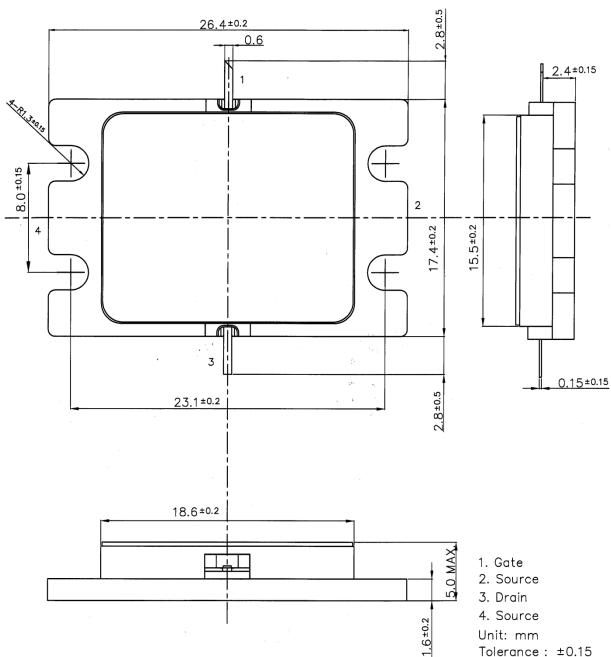
C1, C5 : ATC600L(size:0805), +/- 0.1pF

C6, C7: EMI FILTER MARUWA(FTA352AR102S-S)



• Package Outline

Case Style: I2F



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For Safety, Observe the Following Procedures Environmental Management

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product.
 This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

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